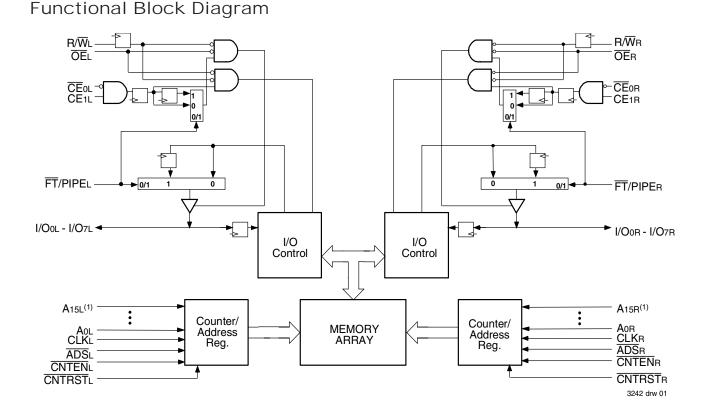
HIGH-SPEED 64/32K x 8 SYNCHRONOUS DUAL-PORT STATIC RAM

Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
 - Commercial: 6/7/9/12/15ns (max.)
 - Industrial: 12ns (max.)
- Low-power operation
 - IDT709089/79S Active: 950mW (typ.)
 - Standby: 5mW (typ.) – IDT709089/79L Active: 950mW (typ.)
 - Standby: 1mW (typ.)
- Flow-Through or Pipelined output mode on either port via the FT/PIPE pin
- Counter enable and reset features

- Dual chip enables allow for depth expansion without additional logic
- * Full synchronous operation on both ports
 - 4ns setup to clock and 1ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 6.5ns clock to data out in the Pipelined output mode
 - Self-timed write allows fast cycle time
 - 10ns cycle time, 100MHz operation in the Pipelined output mode
- * TTL- compatible, single 5V (±10%) power supply
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Available in 100-pin Thin Quad Flatpack (TQFP) package
- * Green parts available, see ordering information



NOTE:

1. A15x is a NC for IDT709079.

IDT709089/79S/L

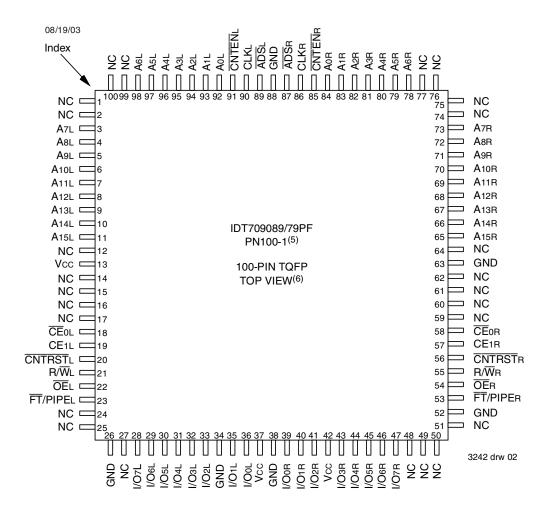
High-Speed 64/32K x 8 Synchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

Description:

The IDT709089/79 is a high-speed 64/32K x 8 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT709089/79 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{CE}o$ and CE_1 , permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 950mW of power.

Pin Configuration^(1,2,3)



- 1. A15x is a NC for IDT709079.
- 2. All Vcc pins must be connected to power supply
- 3. All GND pins must be connected to ground supply.
- 4. Package body is approximately 14mm x 14mm x 1.4mm.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

IDT709089/79S/L High-Speed 64/32K x 8 Synchronous Dual-Port Static RAM

Pin Names

Left Port	Right Port	Names
CE0L, CE1L	CEOR, CE1R	Chip Enables
R/WL	R/Wr	Read/Write Enable
ŌĒL	0 Er	Output Enable
Aol - A15l ⁽¹⁾	Aor - A15r ⁽¹⁾	Address
I/Ool - I/O7l	I/Oor - I/O7r	Data Input/Output
CLKL	CLKr	Clock
ADSL	ADSR	Address Strobe
		Counter Enable
	CNTRST R	Counter Reset
FT/PIPEL	FT /PIPER	Flow-Through/Pipeline
	Vcc	Power
	GND	Ground
		3242 tbl 01

Industrial and Commercial Temperature Ranges

ΝΟΤΕ:

1. A15x is a NC for IDT709079.

Truth Table I—

Read/Write and Enable Control^(1,2,3)

ŌĒ	CLK	CE ₀	CE1	R/W	I/O0-7	Mode
Х	Ŷ	Н	Х	Х	High-Z	Deselected
Х	Ŷ	Х	L	Х	High-Z	Deselected
Х	Ŷ	L	Н	L	Din	Write
L	Ŷ	L	Н	Н	Dout	Read
Н	Х	L	Н	Х	High-Z	Outputs Disabled
						3242 tbl 02

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

2. \overline{ADS} , \overline{CNTEN} , $\overline{CNTRST} = X$.

3. OE is an asynchronous input signal.

Previous Internal External Internal Address MODE ADS CNTRST I/O⁽³⁾ Address Address Used CLK CNTEN Ŷ L⁽⁴⁾ Х Н External Address Used An Х An Dvo (n) î L⁽⁵⁾ Н Н Х An An + 1 Dvo(n+1) Counter Enabled-Internal Address generation Х \uparrow Н Н Н An + 1 An + 1 Divo(n+1) External Address Blocked-Counter disabled (An + 1 reused) L⁽⁴⁾ Х ↑ Х Х Х **A**0 DI/O(0) Counter Reset to Address 0

Truth Table II—Address Counter Control^(1,2)

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

2. \overline{CE}_0 and \overline{OE} = VIL; CE1 and R/W = VIH.

3. Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.

4. ADS is independent of all other signals including CE0 and CE1.

5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CE0 and CE1.

3

IDT709089/79S/L High-Speed 64/32K x 8 Synchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

Recommended Operating Temperature and Supply Voltage⁽¹⁾

Grade	Ambient Temperature	GND	Vcc
Commercial	0°C to +70°C	0V	5.0V <u>+</u> 10%
Industrial	-40°C to +85°C	0V	5.0V <u>+</u> 10%

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Мах.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Ground	0	0	0	V
Vін	Input High Voltage	2.2	-	6.0 ⁽¹⁾	V
VIL	Input Low Voltage	-0.5 ⁽²⁾		0.8	V

NOTES:

3242 tbl 04

3242 tbl 06

1. VTERM must not exceed Vcc + 10%.

2. VIL \geq -1.5V for pulse width less than 10ns.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
Vterm ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
Tbias	Temperature Under Bias	-55 to +125	٥C
Tstg	Storage Temperature	-65 to +150	٥C
Тји	Junction Temperature	+150	٥C
Ιουτ	DC Output Current	50	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vcc+ 10% for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vcc + 10%.
- 3. Ambient Temperature Under DC Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾

$(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter	Conditions ⁽²⁾	Мах.	Unit
Cin	Input Capacitance	VIN = 3dV	9	pF
Cout ⁽³⁾	Output Capacitance	Vout = 3dV	10	pF

NOTES:

- 1. These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.

3. COUT also references CI/O.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (Vcc = 5.0V ± 10%)

		709089/79S/L		9/79S/L	
Symbol	Parameter	Test Conditions	Min.	Мах.	Unit
LI	Input Leakage Current ⁽¹⁾	Vcc = 5.5V, VIN = 0V to Vcc	_	10	μA
llo	Output Leakage Current	$\overline{CE}_0 = V_{IH} \text{ or } CE_1 = V_{IL}, V_{OUT} = 0V \text{ to } V_{CC}$		10	μA
Vol	Output Low Voltage	Iol = +4mA	_	0.4	V
Vон	Output High Voltage	Юн = -4mA	2.4		V

NOTE:

1. At Vcc \leq 2.0V input leakages are undefined.

3242 tbl 08

3242 thl 05

3242 tbl 09

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁶⁾ ($Vcc = 5V \pm 10\%$)

•						9/79X6 I Only		9/79X7 I Only	709089 Com'l		
Symbol	Parameter	Test Condition	Versi	on	Тур. ⁽⁴⁾	Max.	Тур. ⁽⁴⁾	Мах.	Typ. ⁽⁴⁾	Мах.	Unit
Icc	Dynamic Operating Current (Both Ports Active)	$\overline{CE}L$ and $\overline{CE}R=$ VIL Outputs Disabled f = fMAX ⁽¹⁾	COM'L	S L	270 270	585 525	250 250	490 440	210 210	390 350	mA
	(Boin Pons Acive)	T = IMAX''	IND	S L							
ISB1	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ $f = fMAX^{(1)}$	COM'L	S L	80 80	205 175	65 65	170 145	50 50	135 115	mA
	Level Inputs)		IND	S L							
ISB2	Standby Current (One Port - TTL	$\overline{\underline{CE}}^{"}A" = VIL \text{ and } \\ \overline{CE}^{"}B" = VIH^{(3)}$	COM'L	S L	180 180	405 360	160 160	340 295	140 140	270 240	mA
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S L							
ISB3	Full Standby Current (Both Ports -	Both Ports \overline{CER} and $\overline{CEL} \ge VCC - 0.2V$	COM'L	S L	1.0 0.2	15 5	1.0 0.2	15 5	1.0 0.2	15 5	mA
	CMOS Level Inputs)	$V_{IN} \ge V_{CC} - 0.2V \text{ or}$ $V_{IN} \le 0.2V, f = 0^{(2)}$	IND	S L							
ISB4	Full Standby Current (One Port -	$\overline{CE}^{"A"} \leq 0.2V$ and $\overline{CE}^{"B"} \geq Vcc - 0.2V^{(5)}$	COM'L	S L	170 170	395 340	150 150	330 290	130 130	245 225	mA
	CMOS Level Inputs)	$\begin{array}{l} \text{VIN} \geq \text{VCC} - 0.2 \text{V or} \\ \text{VIN} \leq 0.2 \text{V}, \text{ Active Port Outputs} \\ \text{Disabled, } f = f\text{MAX}^{(1)} \end{array}$	IND	S L							

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcvc, using "AC TEST CONDITIONS" at input levels of GND to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. Vcc = 5V, TA = 25°C for Typ, and are not production tested. Icc cc(f=0) = 150mA (Typ).
- 6. 'X' in part numbers indicate power (S or L).

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁶⁾ ($Vcc = 5V \pm 10\%$)(cont'd)

					709089 Coi & I	m'l	709089 Com'l		
Symbol	Parameter	Test Condition	Versi	on	Тур. ⁽⁴⁾	Мах.	Тур. ⁽⁴⁾	Мах.	Unit
ICC	Dynamic Operating Current (Both Ports Active)	$\overline{CE}L$ and $\overline{CE}R=$ VIL Outputs Disabled f = fMAX ⁽¹⁾	COM'L	S L	200 200	345 305	190 190	325 285	mA
			IND	S L	200 200	380 340			
ISB1	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ f = fMAX ⁽¹⁾	COM'L	S L	50 50	110 90	50 50	110 90	mA
	Level Inputs)	IND S		S L	50 50	125 105			
ISB2	Standby Current (One Port - TTL	$\overline{\underline{CE}}^{"}A" = VIL \text{ and } \\ \overline{CE}^{"}B" = VIH^{(3)}$	COM'L	S L	130 130	230 200	120 120	220 190	mA
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S L	130 130	245 215			
ISB3	Full Standby Current (Both Ports -	Both Ports \overline{CER} and $\overline{CEL} \ge VCC - 0.2V$	COM'L	S L	1.0 0.2	15 5	1.0 0.2	15 5	mA
	CMOS Level Inputs)	$ \begin{array}{l} \text{VIN} \geq \text{VCC} - 0.2 \text{V or} \\ \text{VIN} \leq 0.2 \text{V}, \ f = 0^{(2)} \end{array} $	IND	S L	1.0 0.2	15 5			
ISB4	Full Standby Current (One Port -	$\overline{CE}^{*}A^{*} \leq 0.2V$ and $\overline{CE}^{*}B^{*} \geq VCC - 0.2V^{(5)}$	COM'L	S L	120 120	205 185	110 110	195 175	mA
	CMOS Level Inputs) $VIN \ge VCC - 0.2V$ or $VIN \le 0.2V$, Active Port Outputs Disabled, f = fMAX ⁽¹⁾		IND	S L	120 120	220 200			

NOTES:

1. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.

3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

4. Vcc = 5V, TA = 25°C for Typ, and are not production tested. lcc cc(f=0) = 150mA (Typ).

5. $\overline{CE}x = VIL \text{ means } \overline{CE}ox = VIL \text{ and } CE1x = VIH$ $\overline{CE}x = VIH \text{ means } \overline{CEox} = VIH \text{ or } CE1x = VIL$

 $\overline{CE}x \leq 0.2V$ means $\overline{CE}\text{ox} \leq 0.2V$ and CE1x $\geq V\text{cc}~$ - 0.2V

 $\overline{\text{CE}}x \geq V\text{cc}$ - 0.2V means $\overline{\text{CE}}\text{ox} \geq V\text{cc}$ - 0.2V or $\text{CE}\text{ix} \leq 0.2\text{V}$ "X" represents "L" for left port or "R" for right port.

6. 'X' in part numbers indicate power (S or L).

IDT709089/79S/L High-Speed 64/32K x 8 Synchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1,2 and 3

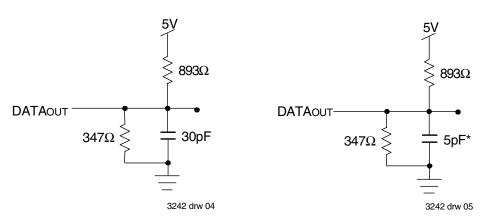
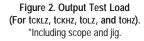


Figure 1. AC Output Test load.



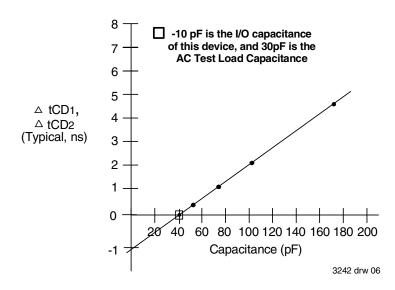


Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)^(3,4) (Vcc = 5V ± 10%)

						709089/79X9 Com'l Only		709089/79X12 Com'l & Ind		9/79X15 I Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Мах.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	19	-	22	-	25	_	30	-	35		ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	10	-	12	-	15	_	20	-	25		ns
tch1	Clock High Time (Flow-Through) ⁽²⁾	6.5	-	7.5	-	12	_	12	-	12		ns
tcl1	Clock Low Time (Flow-Through) ⁽²⁾	6.5	-	7.5	-	12	_	12	-	12		ns
tch2	Clock High Time (Pipelined) ⁽²⁾	4	-	5	-	6	_	8	-	10		ns
tcl2	Clock Low Time (Pipelined) ⁽²⁾	4	-	5	-	6	_	8	-	10		ns
tr	Clock Rise Time		3	_	3	_	3	_	3	_	3	ns
tr	Clock Fall Time	_	3	_	3	_	3	_	3	_	3	ns
tsa	Address Setup Time	3.5		4	—	4		4	—	4		ns
tha	Address Hold Time	0		0	_	1	-	1	—	1	_	ns
tsc	Chip Enable Setup Time	3.5		4	_	4	-	4	—	4	_	ns
thc	Chip Enable Hold Time	0		0	_	1	-	1	—	1	_	ns
tsw	R/W Setup Time	3.5		4	_	4	-	4	—	4	_	ns
thw	R/W Hold Time	0		0	_	1		1		1		ns
tsp	Input Data Setup Time	3.5		4	_	4		4		4		ns
thd	Input Data Hold Time	0		0	_	1		1	—	1	_	ns
tsad	ADS Setup Time	3.5	-	4	-	4	_	4	-	4		ns
thad	ADS Hold Time	0		0	_	1		1	—	1	_	ns
tscn	CNTEN Setup Time	3.5		4	_	4		4		4		ns
thon	CNTEN Hold Time	0		0	_	1		1		1		ns
tsrst	CNTRST Setup Time	3.5	—	4	_	4		4	—	4		ns
thrst	CNTRST Hold Time	0	—	0	_	1		1	—	1		ns
toe	Output Enable to Data Valid		6.5		7.5	_	9		12		15	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2		2		2		2		2		ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	1	7	1	7	ns
tcd1	Clock to Data Valid (Flow-Through) ⁽²⁾		15		18	_	20		25		30	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		6.5		7.5	_	9		12		15	ns
tDC	Data Output Hold After Clock High	2		2	—	2		2		2		ns
tскнz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	2	9	2	9	ns
tcklz	Clock High to Output Low-Z ⁽¹⁾	2		2		2		2	—	2		ns
Port-to-Port D	 Delay		-	•	-	•	•	•	-	•	-	•
tcwdd	Write Port Clock High to Read Data Delay	_	24		28		35		40		50	ns
tccs	Clock-to-Clock Setup Time		9		10		15	l	15		20	ns

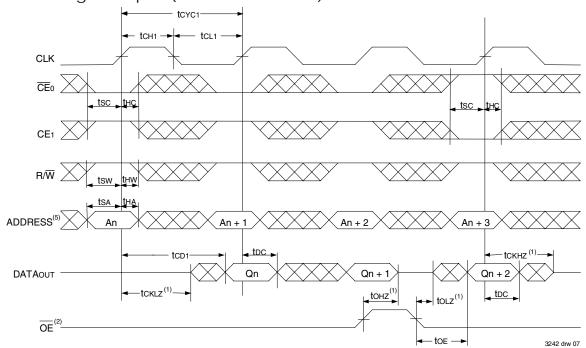
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

2. The Pipelined output parameters (tcvc2, tcb2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcvc1, tcb1) apply when FT/PIPE = VIL for that port.

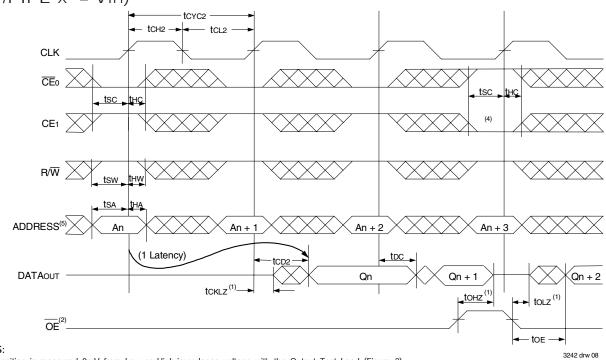
3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

4. 'X' in part number indicates power rating (S or L).

Timing Waveform of Read Cycle for Flow-Through Output (**FT**/PIPE"x" = VIL)^(3,6)

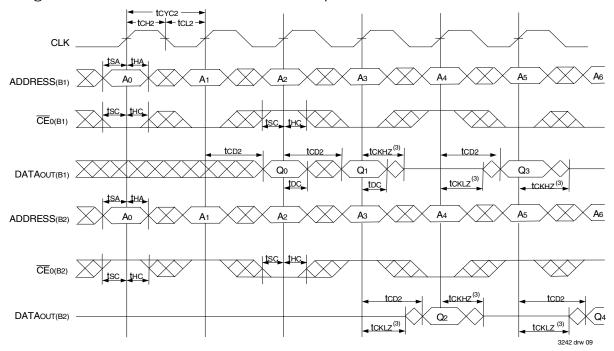


Timing Waveform of Read Cycle for Pipelined Output $(\overline{FT}/PIPE^*X^* = VIH)^{(3,6)}$

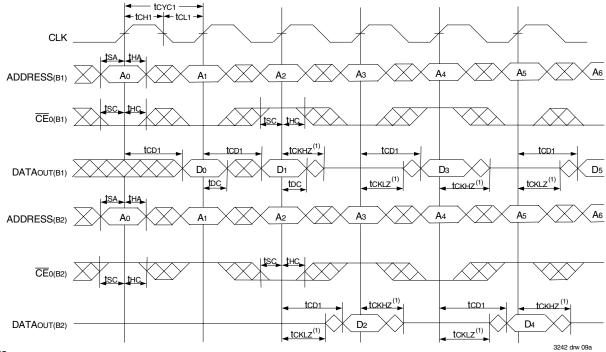


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. OE is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. $\overline{ADS} = VIL$ and $\overline{CNTRST} = VIH$.
- 4. The output is disabled (High-Impedance state) by $\overline{CE}_0 = V_{IH}$ or $CE_1 = V_{IL}$ following the next rising edge of clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. "x" denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Bank Select Pipelined Read^(1,2)

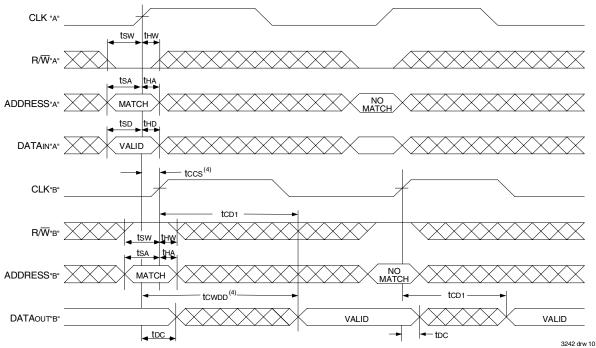


Timing Waveform of a Bank Select Flow-Through Read^(6,7)



- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT709089/79 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{OE} and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/W and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_0 and $\overline{ADS} = V_{IL}$; CE1 and $\overline{CNTRST} = V_{IH}$.
- 5. $\overline{OE} = V_{IL}$ for the Right Port, which is being read from. $\overline{OE} = V_{IH}$ for the Left Port, which is being written to.
- 6. If tccs < maximum specified, then data from right port READ is not valid until the maximum specified for tcwpb.
- If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpp does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A".

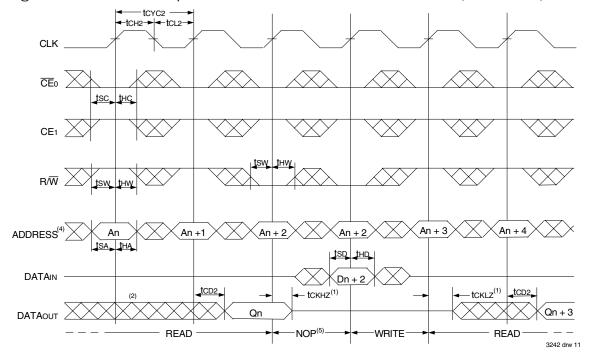
Timing Waveform with Port-to-Port Flow-Through Read^(1,2,3,5)



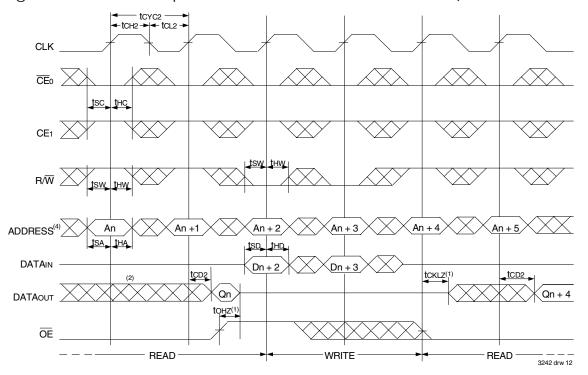
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).

 2. \overline{CE}_0 and $\overline{ADS} = V_{IL}$; CE1 and $\overline{CNTRST} = V_{IH}$.
- 3. $\overline{OE} = V_{IL}$ for the Right Port, which is being read from. $\overline{OE} = V_{IH}$ for the Left Port, which is being written to.
- 4. If tccs < maximum specified, then data from right port READ is not valid until the maximum specified for tcwbb.
- If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwbb does not apply in this case.
- 5. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A".

Timing Waveform of Pipelined Read-to-Write-to-Read ($\overline{OE} = VIL$)⁽³⁾

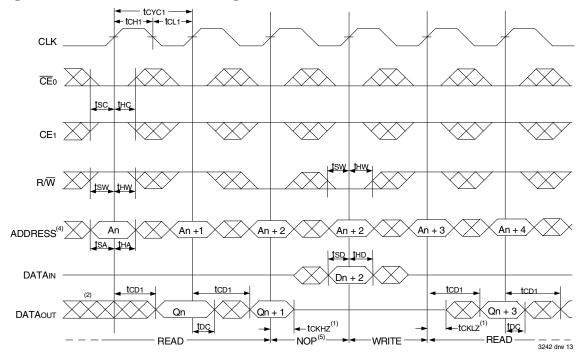


Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** Controlled)⁽³⁾

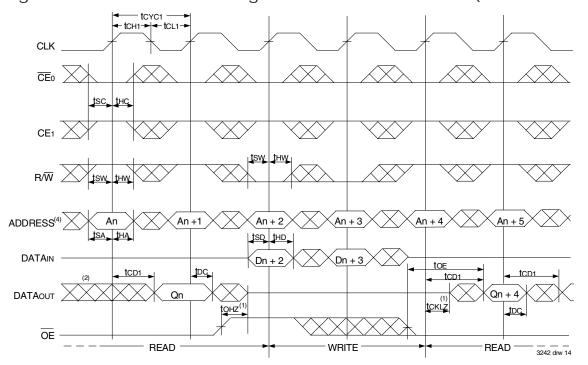


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. \overline{CE}_0 and $\overline{ADS} = VIL$; CE1 and $\overline{CNTRST} = VIH$.
- 4. Addresses do not have to be accessed sequentially since $\overline{\text{ADS}}$ = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform Flow-Through Read-to-Write-to-Read $(\overline{OE} = VIL)^{(3)}$

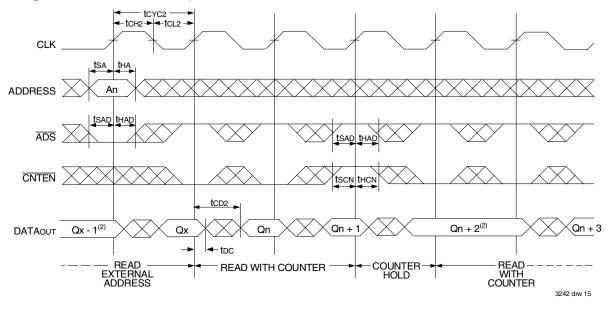


Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽³⁾

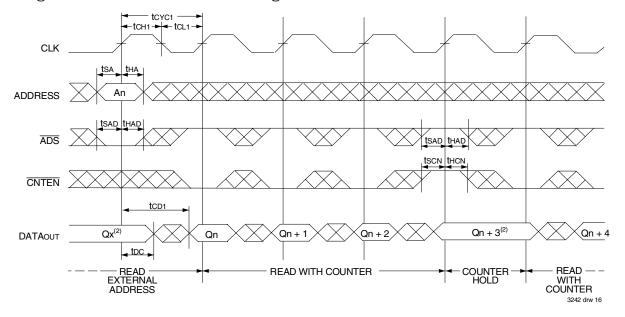


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance is determined by the previous cycle control signals.
- 3. \overline{CE}_0 and $\overline{ADS} = VIL$; CE1 and $\overline{CNTRST} = VIH$.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾

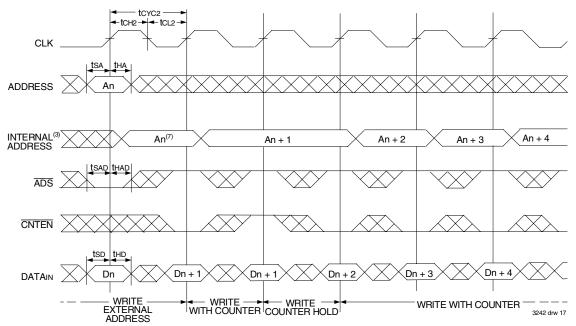


Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾

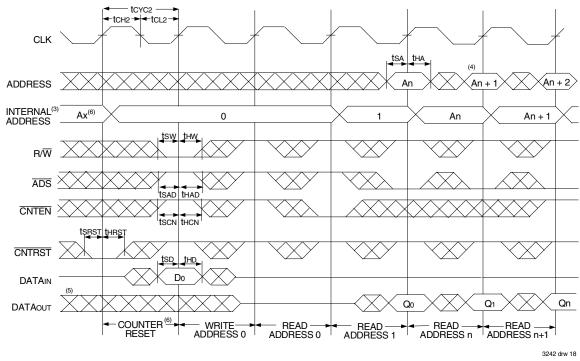


- 1. \overline{CE}_0 and $\overline{OE} = VIL$; CE1, R/W, and $\overline{CNTRST} = VIH$.
- 2. If there is no address change via $\overline{ADS} = VIL$ (loading a new address) or $\overline{CNTEN} = VIL$ (advancing the address), i.e. $\overline{ADS} = VIH$ and $\overline{CNTEN} = VIH$, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)⁽²⁾



- 1. $\overline{CE_0}$ and $R/\overline{W} = V_{IL}$; CE1 and $\overline{CNTRST} = V_{IH}$.
- 2. $\overline{CE}_0 = VIL; CE_1 = VIH.$
- 3. The "Internal Address" is equal to the "External Address" when $\overline{ADS} = VIL$ and equals the counter output when $\overline{ADS} = VIL$.
- Addresses do not have to be accessed sequentially since ADS = Vi∟ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
 Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset. ADDRo will be accessed. Extra cycles are shown here simply for clarification.
- 7. CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1'Address is written to during this cycle.

IDT709089/79S/L

High-Speed 64/32K x 8 Synchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

Functional Description

The IDT709089/79 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

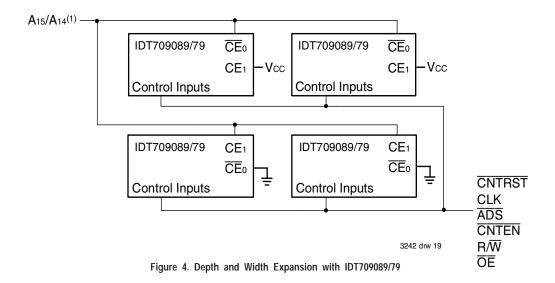
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

A HIGH on \overline{CE} or a LOW on CE1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT709089/79's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with \overline{CE} 0 LOW and CE1 HIGH to reactivate the outputs.

Depth and Width Expansion

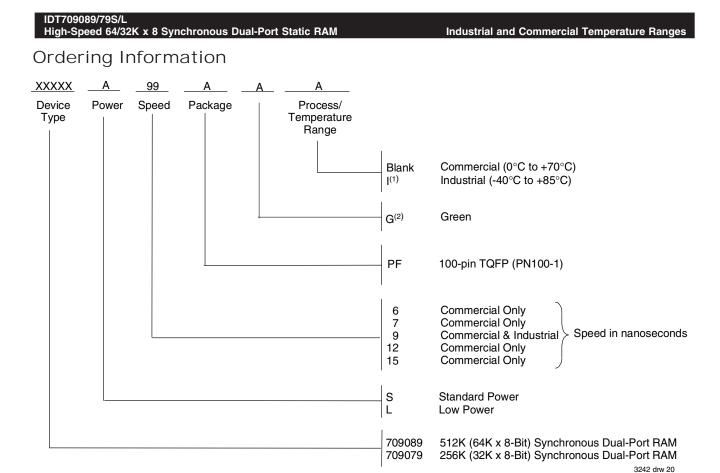
The IDT709089/79 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT709089/79 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 16-bit or wider applications.



NOTE:

1. A15 is for IDT709089, A14 is for IDT709079.



NOTE:

1. Contact your local sales office for industrial temp range for other speeds, packages and powers.

2. Green parts available. For specific speeds, packages and powers contact your sales office.

Ordering Information for Flow-through Devices

Old Flow-through Part	New Combined Part
70908S/L20	709089S/L9
70908S/L25	709089S/L12
70908S/L30	709089S/L15

3242 tbl 12

IDT Clock Solution for IDT709089/79 Dual-Port

IDT Dual-Port Part Number	Dual-Port I/O Specitications		Clock Specifications				IDT	IDT
	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Device	Non-PLL Clock Device
709089/79	5	TTL	9pF	40%	100	150ps	FCT88915TT	49FCT805T 49FCT806T 74FCT807T

Datasheet Document History

1/12/99:		Initiated datasheet document history
		Converted to new format
		Cosmetic and typographical corrections
		Added additional notes to pin configurations
	Page 15	Added Depth and Width Expansion note
6/7/99:	5	Changed drawing format
	Page 4	Deleted note 6 for Table II
11/10/99:	5	Replaced IDT logo
12/22/99:	Page 1	Removed "Separate upper-byte" line
1/12/00:	5	Combined Pipelined 709089 family and Flow-through 70908 family offerings into one data sheet
		Changed ±200mV in waveform notes to 0mV
		Added corresponding part chart with ordering information
2/18/00:	Pages 8 & 9	Changed ±220mV waveform notes to 0mV
	Page 9	Changed "Operation" in heading to "Pipelined Output", fixed drawing 08
	5	Removed PGA package
5/24/00:	Page 3	Changed information in Truth Table II
	Page 4	Increased storage temperature parameters
	5	Clarified TAparameter
	Page 5	DC Electrical parameters-changed wording from "open" to "disabled"
	5	Added Industrial Temperature Ranges and removed related notes
01/10/02:	Page 2	Added date revision for pin configuration
	Page 5 & 7	Removed industrial temp from column headings and values for 15ns from AC & DC Electrical Characteristics
	Page 16	Removed industrial offering from 15ns ordering info and added industrial temp footnote
	Page 1 & 17	Replaced IDT TM logo with \mathbb{R} logo
06/21/04:	0	Consolidated multiple devices into one datasheet
		Removed Preliminary status from datasheet
	Page 4	Added Junction Temperature to Absolute Maximum Ratings Table
	-	Added Ambient Temperature footnote
	Page 5	Added 6ns & 7ns speed DC timing numbers to the DC Electrical Characteristics Table
	Page 8	Added 6ns & 7ns speed AC timing numbers to the AC Electrical Characteristics Table
	Page 17	Added 6ns & 7ns speed grades to ordering information
		Added IDT Clock Solution Table
	Page 1 & 18	Replaced old ${ m I}$ logo with new ${ m TM}$ logo
01/29/09:	Page 17	Removed "IDT" from orderable part number
07/26/10:	Page 1	Added green parts availability to features
	Page 17	Added green indicator to ordering information
	Page 8	In order to correct the header notes of the AC Elect Chars Table and align them with the Industrial temp range
		values located in the table, the commercial TA header note has been removed
	Pages 9-13	In order to correct the footnotes of timing diagrams, CNTEN has been removed to reconcile the footnotes with
		the CNTEN logic definition found in Truth Table II - Address Counter Control



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